



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD22N08S2L-50		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000273813							
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		369.82 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.714	0.46	0.46	4634	4634	
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		634		
	inorganic material	phosphorus	7723-14-0	0.070	0.02		190		
	non noble metal	copper	7440-50-8	234.187	63.34	63.42	633253	634077	
wire	non noble metal	aluminium	7429-90-5	0.928	0.25	0.25	2510	2510	
encapsulation	organic material	carbon black	1333-86-4	1.271	0.34		3438		
	plastics	epoxy resin	-	22.249	6.02		60163		
	inorganic material	silicondioxide	60676-86-0	103.617	28.02	34.38	280186	343787	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10113	10113	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246	
solder	noble metal	silver	7440-22-4	0.043	0.01		116		
	non noble metal	tin	7440-31-5	0.034	0.01		93		
	non noble metal	lead	7439-92-1	1.636	0.44	0.46	4424	4633	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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